

ABSTRACT OF THE DISCLOSURE

An offset measuring mechanism and method used in a bonding apparatus, in which the object plane of a position detection camera is set on a hypothetical bonding working plane, and the image of imaging elements within the imaging plane is projected onto a bonding working plane. Furthermore, the tip end of a bonding tool is aligned with the bonding working plane. The object plane of the offset measuring camera is set on the bonding working plane, and the image on the bonding working plane is projected onto the imaging elements of the imaging plane of the offset measuring camera. The imaging elements detect the projected image of the imaging elements of the position detection camera or the image of the tip end of the bonding tool and output this data to the image position measuring part or tool position measuring section of the control block.